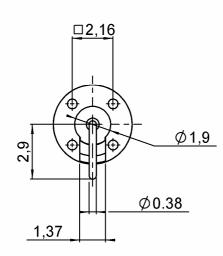
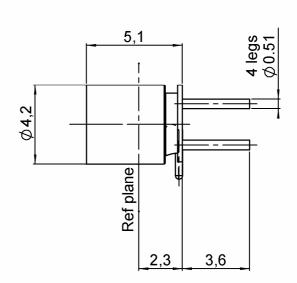
PIN IN PASTE - LIMITED DETENT

R222.428.300

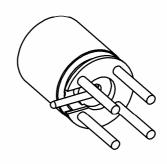
Series: SMP







Scale 1:1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	STAINLESS STEEL + BRASS BERYLLIUM COPPER - PTFE -	PASSIVATED + GOLD 0.5 OVER NICKEL 2 GOLD 1.27 OVER NICKEL 1.27 -
-	-	-

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



PIN IN PASTE - LIMITED DETENT

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Series: SMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-18 GHz

Frequency **0-18** GHz VSWR **1.15*** + **0,0000** x F(0)

VSWR 1.15* + 0,0000 x F(GHz) Maxi Insertion loss 0.12 $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 5000 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

Compliant with MIL-STD-348
*At 12.4GHz - performance strongly depends on lay out and pcb material

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0,3500** g

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Series: SMP

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

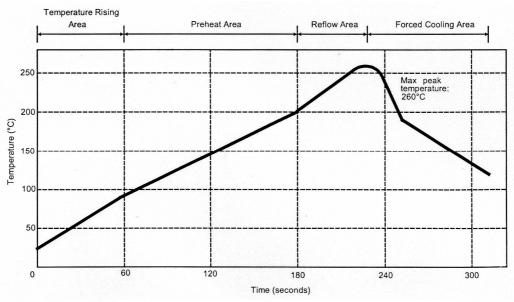
We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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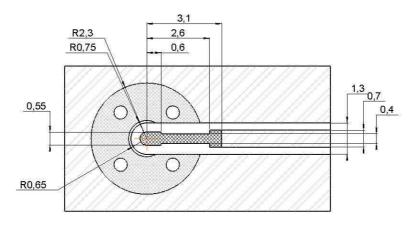
PIN IN PASTE - LIMITED DETENT

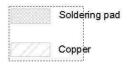
R222.428.300

Series: SMP

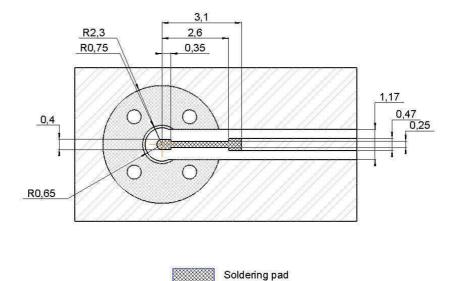
RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides : Add vias between both sides along upper ground plane according to engineering practise





Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise





Issue: 0914 C

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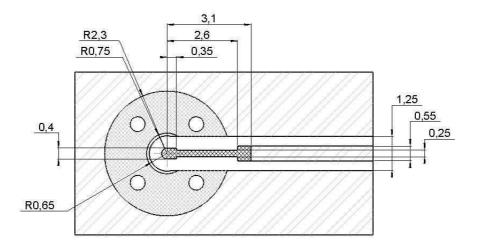


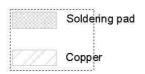
PIN IN PASTE - LIMITED DETENT

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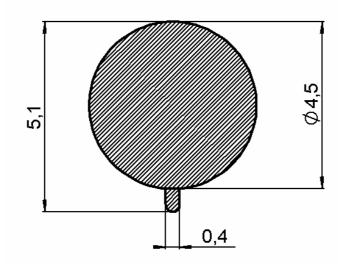
Series: SMP

Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise





SHADOW FOR VIDEO CAMERA



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